

MC74LCX158

Low-Voltage CMOS Quad 2-Input Multiplexer

With 5 V-Tolerant Inputs (Inverting)

The MC74LCX158 is a high performance, quad 2-input inverting multiplexer operating from a 2.3 to 3.6 V supply. High impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance. A V_I specification of 5.5 V allows MC74LCX158 inputs to be safely driven from 5 V devices.

Four bits of data from two sources can be selected using the Select and Enable inputs. The four outputs present the selected data in the inverted form. The MC74LCX158 can also be used as a function generator. Current drive capability is 24 mA at the outputs.

Features

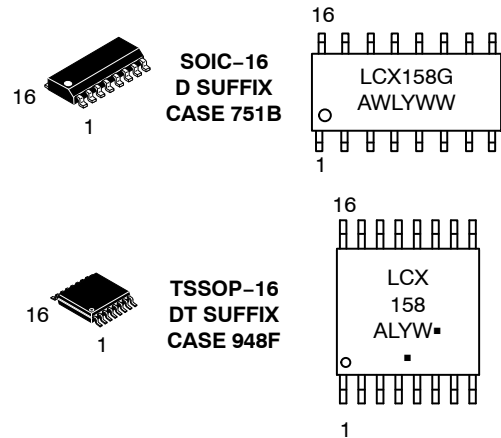
- Designed for 2.3 to 3.6 V V_{CC} Operation
- 5 V Tolerant Inputs – Interface Capability With 5 V TTL Logic
- LVTTL Compatible
- LVCMOS Compatible
- 24 mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current (10 μ A) Substantially Reduces System Power Requirements
- Latchup Performance Exceeds 500 mA
- ESD Performance:
 - ◆ Human Body Model >2000 V
 - ◆ Machine Model >200 V
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant



ON Semiconductor®

<http://onsemi.com>

MARKING DIAGRAMS



A = Assembly Location
WL, L = Wafer Lot
Y = Year
WW, W = Work Week
G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

MC74LCX158

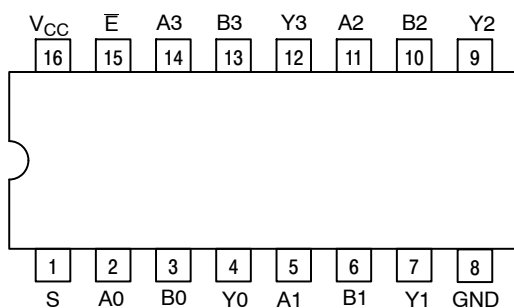


Figure 1. Pinout: 16-Lead Plastic Package (Top View)

PIN NAMES

Pins	Function
An	Source 0 Data Inputs
Bn	Source 1 Data Inputs
\bar{E}	Enable Input
S	Select Input
Yn	Outputs

TRUTH TABLE

Inputs		Outputs
Output Enable	Select	Y0–Y3
H	X	H
L	L	A0–A3
L	H	B0–B3

X = Don't Care
 A0–A3, B0–B3 = The levels of the respective
 Data–Word Inputs

PIN DESCRIPTIONS

INPUTS

A0–A3 (Pins 2, 5, 11, 14)

Nibble A inputs. The data present on these pins is transferred to the outputs when the Select input is at a low level and the Output Enable input is at a low level. The data is presented to the outputs in inverted form for the LCX158.

B0–B3 (Pins 3, 6, 10, 13)

Nibble B inputs. The data present on these pins is transferred to the outputs when the Select input is at a high level and the Output Enable input is at a low level. The data is presented to the outputs in inverted form for the LCX158.

OUTPUTS

Y0–Y3 (Pins 4, 7, 9, 12)

Data outputs. The selected input nibble is presented at these outputs when the Output Enable input is at a low level. The data present on these pins is in its inverted form for the LCX158. For the Output Enable input at a high level, the outputs are at a high level for the LCX158.

Select (Pin 1)

Nibble select. This input determines the data word to be transferred to the outputs. A low level on this input selects the A inputs and a high level selects the B inputs.

CONTROL INPUTS

Enable (Pin 15)

Output Enable input. A low level on this input allows the selected data to be presented at the outputs. A high level on this input sets all of the outputs to a high level for the LCX158.

MC74LCX158

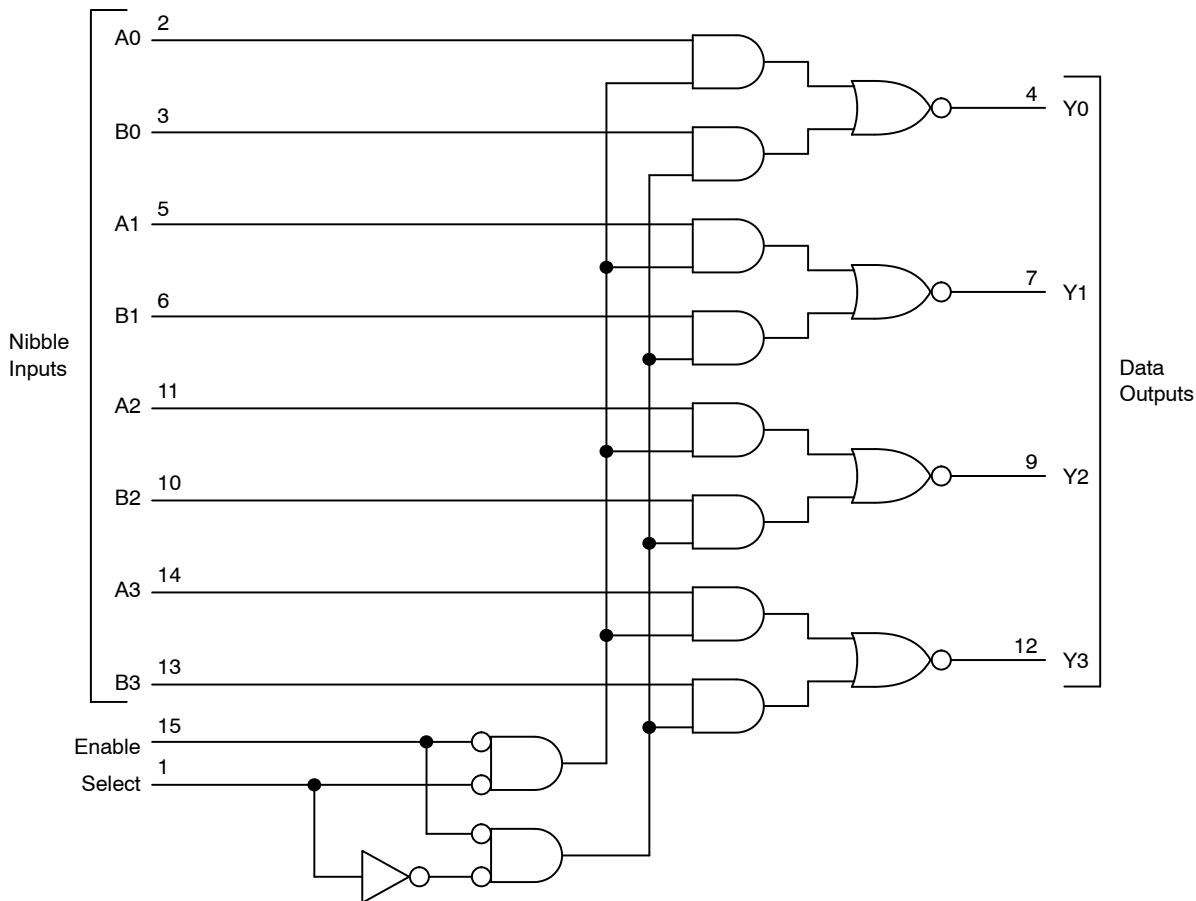


Figure 2. Expanded Logic Diagram

ORDERING INFORMATION

Device	Package	Shipping [†]
MC74LCX158DG	SOIC-16 (Pb-Free)	48 Units / Rail
MC74LCX158DR2G	SOIC-16 (Pb-Free)	2500 Tape & Reel
MC74LCX158DTG	TSSOP-16 (Pb-Free)	96 Units / Rail
MC74LCX158DTR2G	TSSOP-16 (Pb-Free)	2500 Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MC74LCX158

MAXIMUM RATINGS

Symbol	Parameter	Value	Condition	Units
V _{CC}	DC Supply Voltage	-0.5 to +7.0		V
V _I	DC Input Voltage	-0.5 ≤ V _I ≤ +7.0		V
V _O	DC Output Voltage	-0.5 ≤ V _O ≤ V _{CC} + 0.5	Output in HIGH or LOW State (Note 1)	V
I _{IK}	DC Input Diode Current	-50	V _I < GND	mA
I _{OK}	DC Output Diode Current	-50	V _O < GND	mA
		+50	V _O > V _{CC}	mA
I _O	DC Output Source/Sink Current	±50		mA
I _{CC}	DC Supply Current Per Supply Pin	±100		mA
I _{GND}	DC Ground Current Per Ground Pin	±100		mA
T _{STG}	Storage Temperature Range	-65 to +150		°C
MSL	Moisture Sensitivity		Level 1	

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. I_O absolute maximum rating must be observed.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Typ	Max	Units
V _{CC}	Supply Voltage Operating Data Retention Only	2.0 1.5	2.3 to 3.3	3.6 3.6	V
V _I	Input Voltage	0		5.5	V
V _O	Output Voltage (HIGH or LOW State) (3-State)	0		V _{CC}	V
I _{OH}	HIGH Level Output Current V _{CC} = 3.0 V – 3.6 V V _{CC} = 2.7 V – 3.0 V V _{CC} = 2.3 V – 2.7 V			-24 -12 -8	mA
I _{OL}	LOW Level Output Current V _{CC} = 3.0 V – 3.6 V V _{CC} = 2.7 V – 3.0 V V _{CC} = 2.3 V – 2.7 V			+24 +12 +8	mA
T _A	Operating Free-Air Temperature	-40		+85	°C
Δt/ΔV	Input Transition Rise or Fall Rate, V _{IN} from 0.8 V to 2.0 V, V _{CC} = 3.0 V	0		10	ns/V

MC74LCX158

DC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic	Condition	T _A = -40°C to +85°C		Units
			Min	Max	
V _{IH}	Minimum HIGH Level Input Voltage (Note 2)	2.3 V ≤ V _{CC} ≤ 2.7 V 2.7 V ≤ V _{CC} ≤ 3.0 V 3.0 V ≤ V _{CC} ≤ 3.6 V	1.7 2.0 2.0		V
V _{IL}	Maximum LOW Level Input Voltage (Note 2)	2.3 V ≤ V _{CC} ≤ 2.7 V 2.7 V ≤ V _{CC} ≤ 3.0 V 3.0 V ≤ V _{CC} ≤ 3.6 V		0.7 0.8 0.8	V
V _{OH}	Minimum HIGH Level Output Voltage	2.3 V ≤ V _{CC} ≤ 3.6 V; I _{OH} = -100 μA V _{CC} = 2.3 V; I _{OH} = -8 mA V _{CC} = 2.7 V; I _{OH} = -12 mA V _{CC} = 3.0 V; I _{OH} = -18 mA V _{CC} = 3.0 V; I _{OH} = -24 mA	V _{CC} - 0.2 1.7 2.2 2.4 2.2		V
V _{OL}	Maximum LOW Level Output Voltage	2.3 V ≤ V _{CC} ≤ 3.6 V; I _{OH} = 100 μA V _{CC} = 2.3 V; I _{OH} = 8 mA V _{CC} = 2.7 V; I _{OH} = 12 mA V _{CC} = 3.0 V; I _{OH} = 16 mA V _{CC} = 3.0 V; I _{OH} = 24 mA		0.2 0.7 0.4 0.4 0.55	V
I _{OFF}	Power Off Leakage Current	V _{CC} = 0, V _{IN} = 5.5 V or V _{OUT} = 5.5 V		10	μA
I _{IN}	Input Leakage Current	V _{CC} = 3.6 V, V _{IN} = 5.5 V or GND		±5	μA
I _{CC}	Quiescent Supply Current	V _{CC} = 3.6 V, V _{IN} = 5.5 V or GND		10	μA
ΔI _{CC}	Increase in I _{CC} per Input	2.3 ≤ V _{CC} ≤ 3.6 V; V _{IH} = V _{CC} - 0.6 V		500	μA

2. These values of V_I are used to test DC electrical characteristics only.

AC CHARACTERISTICS

Symbol	Parameter	Limits						Units
		T _A = -40°C to +85°C						
		V _{CC} = 3.0 V ± 3.6 V		V _{CC} = 2.7 V		V _{CC} = 2.3 V to 2.7 V		
		C _L = 50 pF		C _L = 50 pF		C _L = 30 pF		
		Min	Max	Min	Max	Min	Max	
t _{PLH}	Propagation Delay	1.0	6.5	1.0	7.5	1.0	8.5	ns
t _{PHL}	A or B to Y	1.0	6.5	1.0	7.5	1.0	8.5	
t _{PLH}	Propagation Delay	1.0	7.0	1.0	8.0	1.0	9.0	ns
t _{PHL}	S to Y	1.0	7.0	1.0	8.0	1.0	9.0	
t _{PLH}	Propagation Delay	1.0	7.0	1.0	8.0	1.0	9.0	ns
t _{PHL}	Output Enable to Y	1.0	7.0	1.0	8.0	1.0	9.0	
t _{OSHL}	Output-to-Output Skew		1.0					ns
t _{OSLH}			1.0					

DYNAMIC SWITCHING CHARACTERISTICS

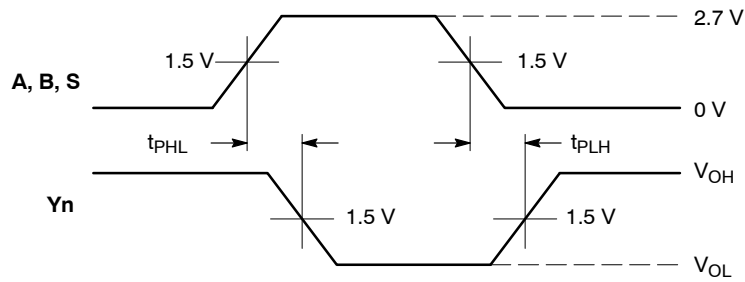
Symbol	Characteristic	Condition	T _A = +25°C			Units
			Min	Typ	Max	
V _{OLP}	Dynamic LOW Peak Voltage (Note 3)	V _{CC} = 3.3 V, C _L = 50 pF, V _{IH} = 3.3 V, V _{IL} = 0 V		0.8		V
V _{OLV}	Dynamic LOW Valley Voltage (Note 3)	V _{CC} = 3.3 V, C _L = 50 pF, V _{IH} = 3.3 V, V _{IL} = 0 V		0.8		V

3. Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

CAPACITIVE CHARACTERISTICS

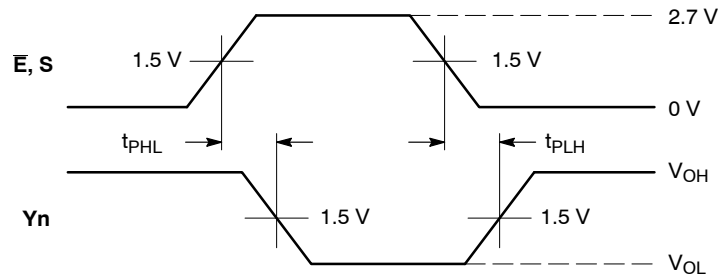
Symbol	Parameter	Condition	Typical	Units
C _{IN}	Input Capacitance	V _{CC} = 3.3 V, V _I = 0 V or V _{CC}	7	pF
C _{OUT}	Output Capacitance	V _{CC} = 3.3 V, V _I = 0 V or V _{CC}	8	pF
C _{PD}	Power Dissipation Capacitance	10 MHz, V _{CC} = 3.3 V, V _I = 0 V or V _{CC}	25	pF

MC74LCX158



WAVEFORM 1 - INVERTING PROPAGATION DELAYS

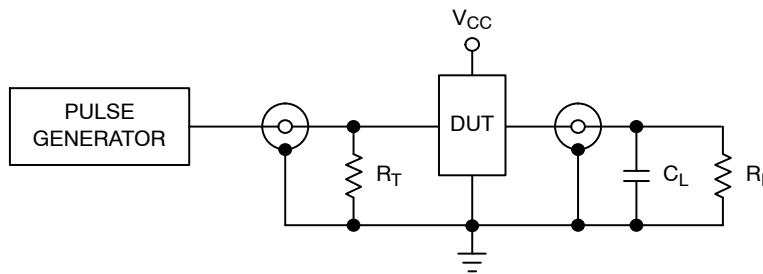
$t_R = t_F = 2.5 \text{ ns}$, 10% to 90%; $f = 1 \text{ MHz}$; $t_W = 500 \text{ ns}$



WAVEFORM 2 - INVERTING PROPAGATION DELAYS

$t_R = t_F = 2.5 \text{ ns}$, 10% to 90%; $f = 1 \text{ MHz}$; $t_W = 500 \text{ ns}$

Figure 3. AC Waveforms



$C_L = 50 \text{ pF}$ or equivalent (Includes jig and probe capacitance)

$R_L = R_1 = 500 \Omega$ or equivalent

$R_T = Z_{OUT}$ of pulse generator (typically 50Ω)

Figure 4. Test Circuit

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



SCALE 1:1

SOIC-16 CASE 751B-05 ISSUE K

DATE 29 DEC 2006



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

- | | | | |
|---|---|---|---|
| <p>STYLE 1:</p> <p>PIN 1. COLLECTOR
2. BASE
3. EMITTER
4. NO CONNECTION
5. EMITTER
6. BASE
7. COLLECTOR
8. COLLECTOR
9. BASE
10. EMITTER
11. NO CONNECTION
12. EMITTER
13. BASE
14. COLLECTOR
15. EMITTER
16. COLLECTOR</p> | <p>STYLE 2:</p> <p>PIN 1. CATHODE
2. ANODE
3. NO CONNECTION
4. CATHODE
5. CATHODE
6. NO CONNECTION
7. ANODE
8. CATHODE
9. CATHODE
10. ANODE
11. NO CONNECTION
12. CATHODE
13. CATHODE
14. NO CONNECTION
15. ANODE
16. CATHODE</p> | <p>STYLE 3:</p> <p>PIN 1. COLLECTOR, DYE #1
2. BASE, #1
3. EMITTER, #1
4. COLLECTOR, #1
5. COLLECTOR, #2
6. BASE, #2
7. EMITTER, #2
8. COLLECTOR, #2
9. COLLECTOR, #3
10. BASE, #3
11. EMITTER, #3
12. COLLECTOR, #3
13. COLLECTOR, #4
14. BASE, #4
15. EMITTER, #4
16. COLLECTOR, #4</p> | <p>STYLE 4:</p> <p>PIN 1. COLLECTOR, DYE #1
2. COLLECTOR, #1
3. COLLECTOR, #2
4. COLLECTOR, #2
5. COLLECTOR, #3
6. COLLECTOR, #3
7. COLLECTOR, #4
8. COLLECTOR, #4
9. BASE, #4
10. EMITTER, #4
11. BASE, #3
12. EMITTER, #3
13. BASE, #2
14. EMITTER, #2
15. BASE, #1
16. EMITTER, #1</p> |
| <p>STYLE 5:</p> <p>PIN 1. DRAIN, DYE #1
2. DRAIN, #1
3. DRAIN, #2
4. DRAIN, #2
5. DRAIN, #3
6. DRAIN, #3
7. DRAIN, #4
8. DRAIN, #4
9. GATE, #4
10. SOURCE, #4
11. GATE, #3
12. SOURCE, #3
13. GATE, #2
14. SOURCE, #2
15. GATE, #1
16. SOURCE, #1</p> | <p>STYLE 6:</p> <p>PIN 1. CATHODE
2. CATHODE
3. CATHODE
4. CATHODE
5. CATHODE
6. CATHODE
7. CATHODE
8. CATHODE
9. ANODE
10. ANODE
11. ANODE
12. ANODE
13. ANODE
14. ANODE
15. ANODE
16. ANODE</p> | <p>STYLE 7:</p> <p>PIN 1. SOURCE N-CH
2. COMMON DRAIN (OUTPUT)
3. COMMON DRAIN (OUTPUT)
4. GATE P-CH
5. COMMON DRAIN (OUTPUT)
6. COMMON DRAIN (OUTPUT)
7. COMMON DRAIN (OUTPUT)
8. SOURCE P-CH
9. SOURCE P-CH
10. COMMON DRAIN (OUTPUT)
11. COMMON DRAIN (OUTPUT)
12. COMMON DRAIN (OUTPUT)
13. GATE N-CH
14. COMMON DRAIN (OUTPUT)
15. COMMON DRAIN (OUTPUT)
16. SOURCE N-CH</p> | |

SOLDERING FOOTPRINT



DIMENSIONS: MILLIMETERS

DOCUMENT NUMBER:	98ASB42566B	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	SOIC-16	PAGE 1 OF 1

ON Semiconductor and ON are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®



TSSOP-16
CASE 948F-01
ISSUE B

DATE 19 OCT 2006



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

SOLDERING FOOTPRINT



GENERIC MARKING DIAGRAM*



- XXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- G or ■ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present.

DOCUMENT NUMBER:	98ASH70247A	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	TSSOP-16	PAGE 1 OF 1

ON Semiconductor and ON are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.